2SB1399

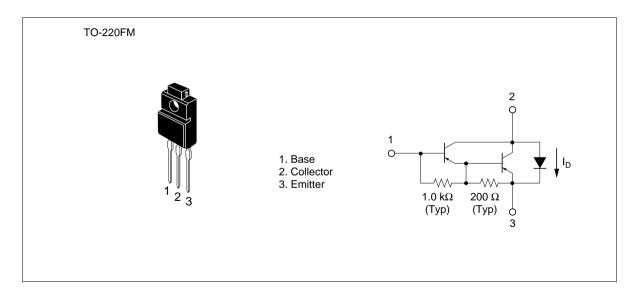
Silicon PNP Triple Diffused

HITACHI

Application

Low frequency power amplifier

Outline





2SB1399

Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	-120	V
Collector to emitter voltage	V _{CEO}	-120	V
Emitter to base voltage	V_{EBO}	– 7	V
Collector current	I _c	-10	A
Collector peak current	I _{C (peak)}	– 15	A
Collector power dissipation	P _c	2	W
	P _c *1	30	
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C
C to E diode forward current	I _D *1	10	A

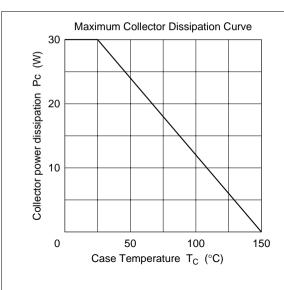
Note: 1. Value at $T_c = 25^{\circ}C$.

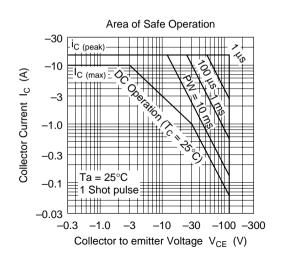
Electrical Characteristics (Ta = 25°C)

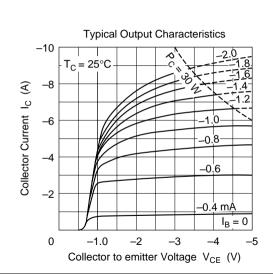
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-120	_	_	V	$I_{c} = -0.1 \text{ mA}, I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-120	_	_	V	$I_{\text{C}} = -25 \text{ mA}, R_{\text{BE}} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-7	_	_	V	$I_{E} = -50 \text{ mA}, I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	-10	μΑ	$V_{CB} = -100 \text{ V}, I_{E} = 0$
	I _{CEO}	_	_	-10	_	$V_{CE} = -100 \text{ V}, R_{BE} = \infty$
DC current transfer ratio	\mathbf{h}_{FE}	1000	_	20000		$V_{CE} = -3 \text{ V}, I_{C} = -5 \text{ A}^{*1}$
Collector to emitter saturation	$V_{\text{CE (sat)1}}$	_	_	-1.5	V	$I_{\rm C} = -5 \text{ A}, I_{\rm B} = 10 \text{ mA}^{*1}$
voltage	V _{CE (sat)2}	_	_	-3.0	_	$I_{\rm C} = -10 \text{ A}, I_{\rm B} = -100 \text{ mA}^{*1}$
Base to emitter saturation	$V_{\text{BE (sat)1}}$	_	_	-2.0	V	$I_{\rm C} = -5 \text{ A}, I_{\rm B} = 10 \text{ mA}^{*1}$
voltage	V _{BE (sat)2}	_	_	-3.5	_	$I_{\rm C} = -10 \text{ A}, I_{\rm B} = -100 \text{ mA}^{*1}$
C to E diode forward voltage	V _D	_	_	3.0	V	I _D = 10 A*1

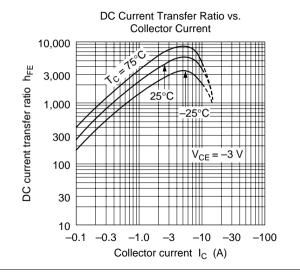
Note: 1. Pulse Test.

See switching characteristic curve of 2SB955(K).

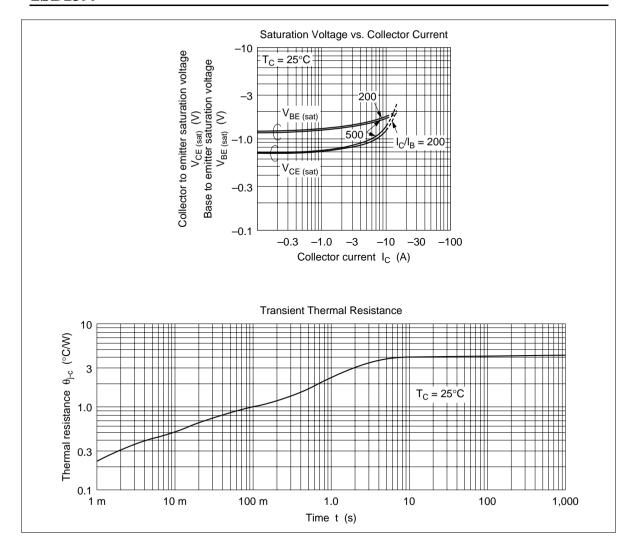


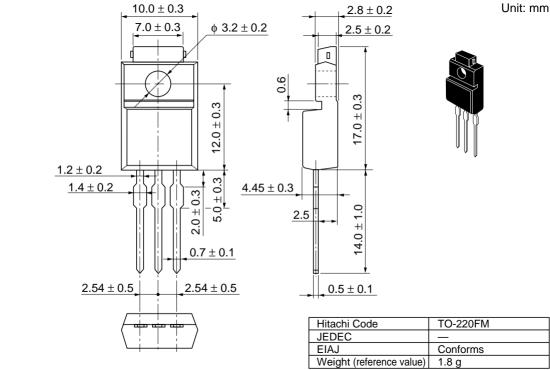






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